

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows.

1. (Cancelled)
2. (Cancelled)
3. (Previously Presented) A support strip comprising:
at least one roughly parallel gripping area; and
a first support element and at least a second support element,
wherein the first support element comprises a first set of conducting elements, each of said
conducting elements having a contact pad and a wiring pad,
wherein the second support element comprises a second set of conducting elements, each of
said conducting elements having a contact pad and a wiring pad, and
wherein the first support element is connected to the at least one gripping area using at least
a first snap-off junction area,
wherein the second support element is connected to the at least one gripping area using at
least a second snap-off junction area, and
wherein each support element is configured to be overmoulded to obtain respectively a first
and at least a second data carrier body.
4. (Previously Presented) The support strip according to claim 3, wherein the support element
is a support grid.
5. (Previously Presented) The support strip according to claim 3, wherein the support element
comprises a first set of foolproofing holes.
6. (Previously Presented) The support strip according to claim 5, wherein the support element
comprises a second set of foolproofing holes.

7. (Previously Presented) The support strip according to claim 4, wherein the support grid is metallic.
8. (Previously Presented) The support strip according to claim 3, wherein the first support element has a contour whose geometry substantially complies with GSM 11.11.
9. (Original) The support strip according to claim 3, wherein the support element is arranged to receive an electronic component.
10. (Previously Presented) The support strip according to claim 9, wherein the electronic component is a microcircuit.
11. (Previously Presented) The support strip of according to claim 3, wherein the first support element is overmoulded using a thermoplastic.
- 12-18. (Cancelled)
19. (Currently Amended) The support strip according to claim 3, wherein a microcircuit is connected to [[the]] at least one wiring pad in the first set of conducting elements after the first support element has been overmoulded.
20. (Cancelled)